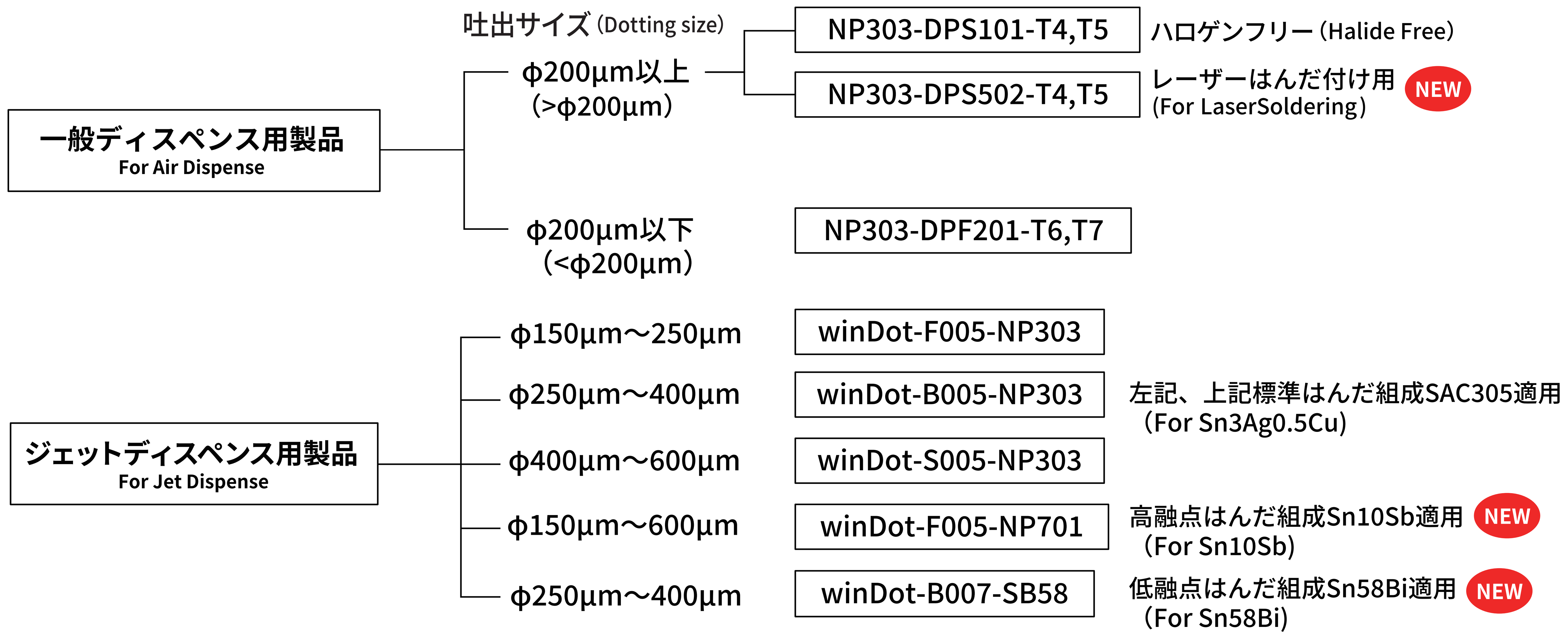
3D構造組立へ！微細ディスペンス用はんだペースト！

For 3D structural assembly! Solder paste for micro-dispensing!

ディスペンス用製品ラインナップ Product line-up for dispensing



winDot-F005-NP701 (ジェットディスペンス用)

(forJet Dispensing)

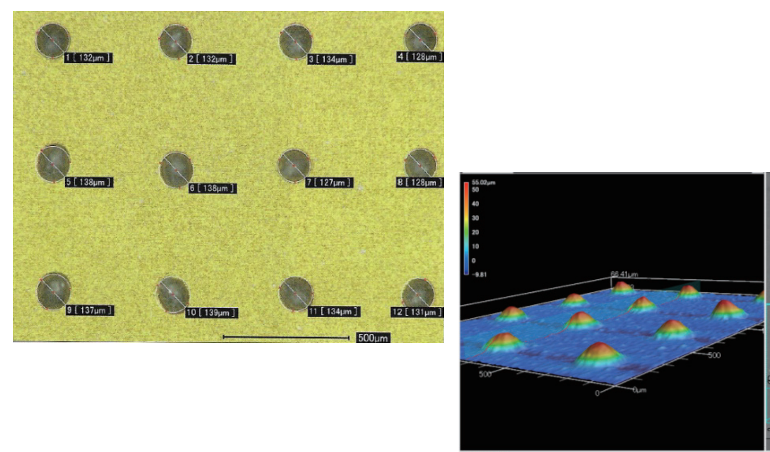
Jet Dispense 用はんだに高融点組成のはんだ(Sn10Sb)が新たに追加

High temperature solder(Sn10Sb) also added on line-up of Jet Dispense products

微細吐出の特性
Property of fine dispense

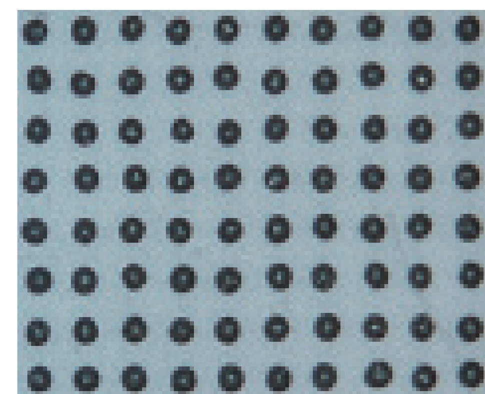
Type7ペーストでϕ200μm 以下の安定吐出を実現

Capable of dispensing ϕ200μm or less by Type7 paste!

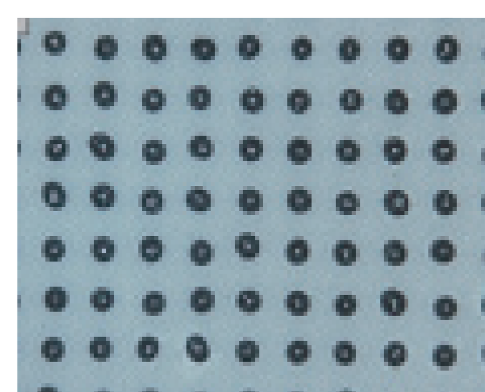


連続吐出性能

Continuous dispensing performance



初期
Initial stage



30万点
300,000dot

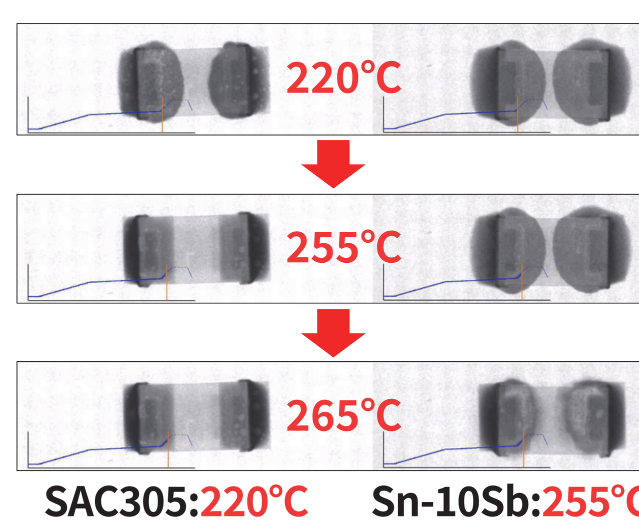
高融点はんだの特性
Property of high temperature solder

次工程での部品内部接合の再溶融防止に高融点はんだを適用

Apply high temperature solder to prevent from re-melting inside component at next process

溶融開始温度比較

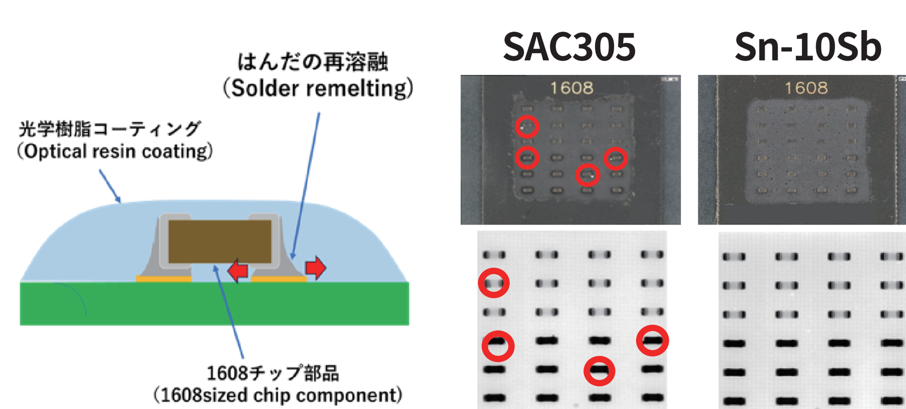
Melting temperature comparison



SAC305:220℃　Sn-10Sb:255℃

接合部の樹脂モールド後の再加熱によるはんだ再溶融挙動有無を確認

Check the re-melting after resin molding



再加熱後にはんだの移動が確認された部分を赤枠で表示

Movement of solder can be seen in red circles

NP303-DPS502-T4

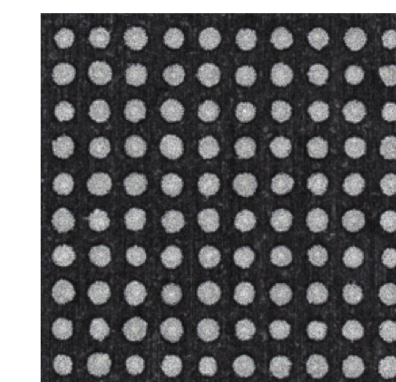
(一般ディスペンス用：レーザーはんだ付け対応)

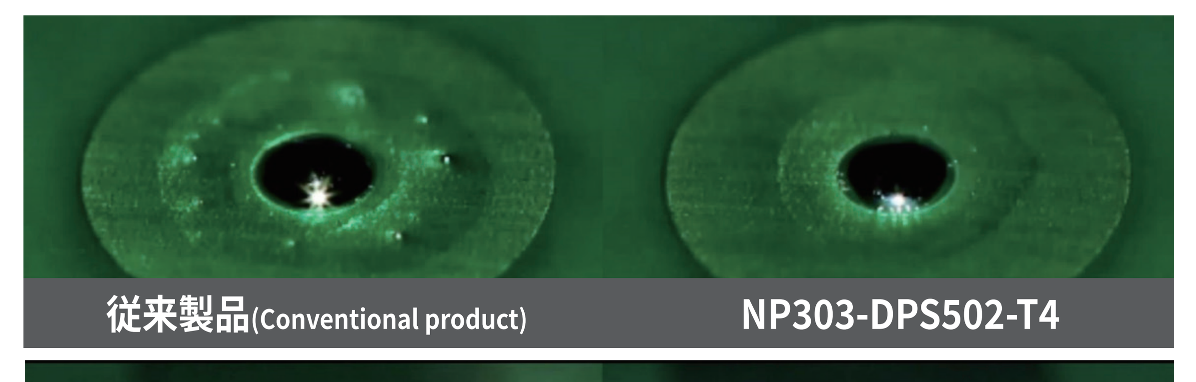
(For air dispense:applicable to laser soldering)

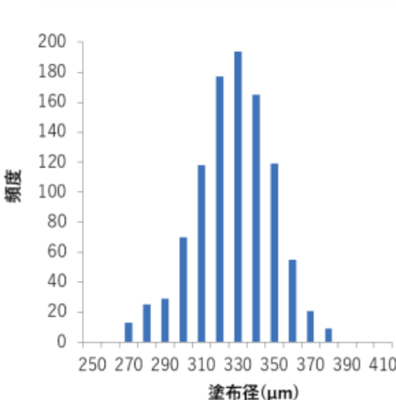
スルーホールリフローに対応
For through-hole-reflow process

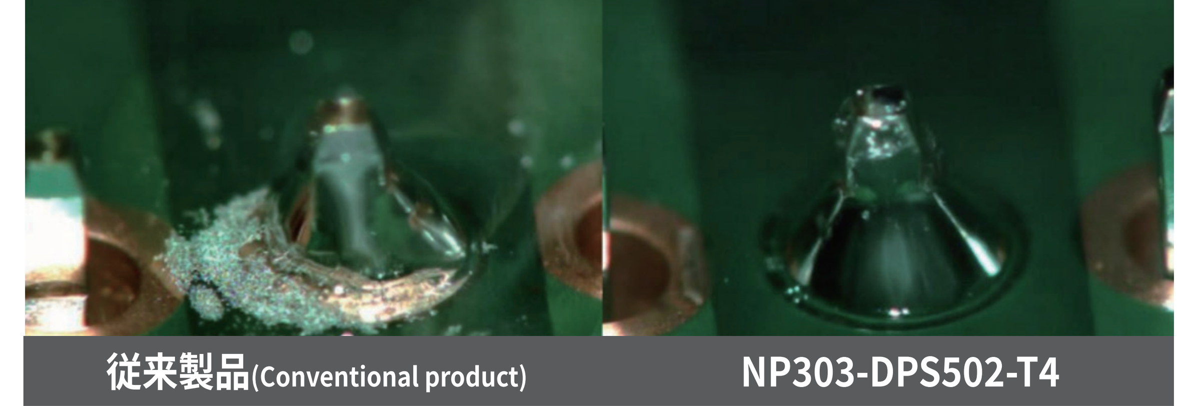
ディスペンス時の充填性とレーザーはんだ付け時の凝集性が良好
Stable fillability to the hole at dispensing and excellent solderability at laser Soldering.

レーザー急加熱時のこぼれボール抑制で優れた凝集性
Excellent solderability with reduced solder ball outflow during rapid laser heating

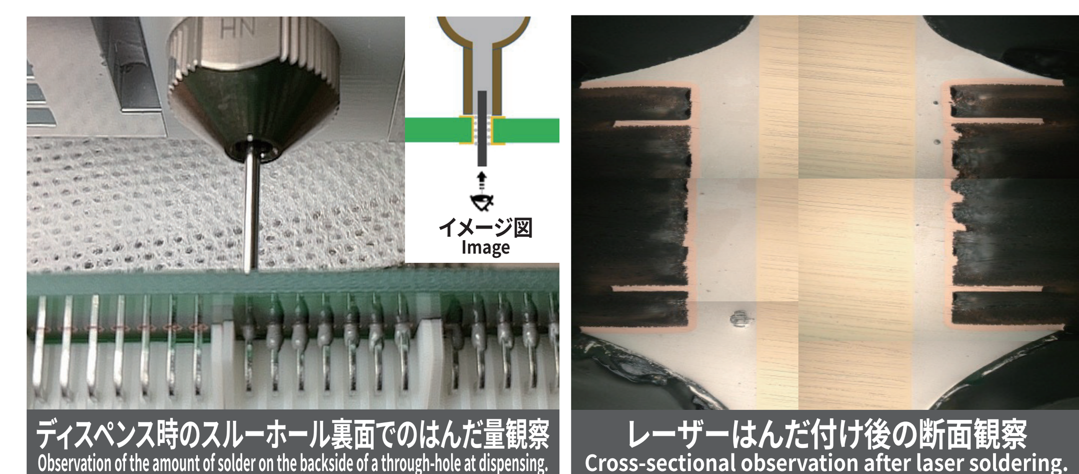








ディスペンス時のスルーホールへの安定かつ十分なはんだペーストの充填性
Stable and sufficient filling of through-holes with solder paste at dispensing



スルーホール裏面のはんだ充填量比較
Comparison of the amount of solder on the backside of a through-hole at dispensing.

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